

# 74F656A

Octal buffer/driver with parity; non-inverting; 3-state

Rev. 04 — 5 February 2010

Product data sheet

## 1. General description

The 74F656A is an octal buffer and line driver with parity generation/checking. The 74F656A can be used as memory address driver, clock driver and bus-oriented transmitter/receiver. The inclusion of parity generation/checking improves PCB density.

## 2. Features

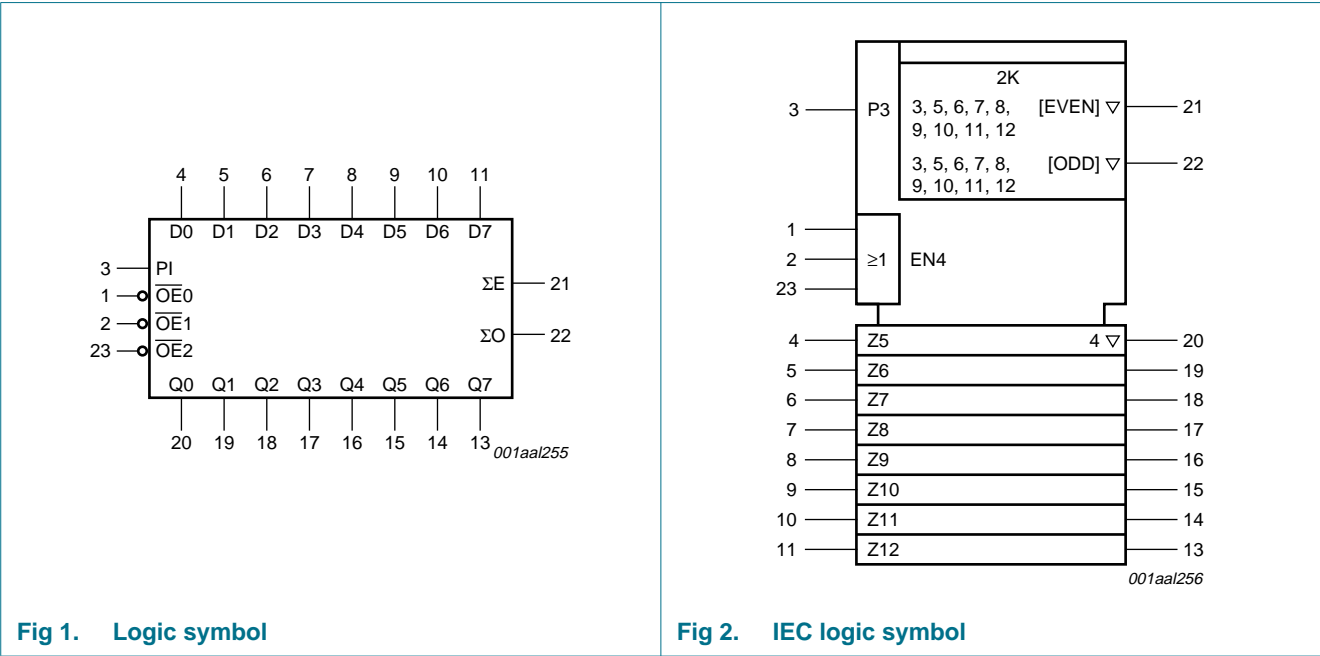
- Combines 74F244 and 74F280A functions in one device
- High impedance NPN base inputs for reduced input current (40  $\mu$ A in HIGH and LOW states)
- $I_{IL}$  = 20  $\mu$ A compared to 600  $\mu$ A in FAST family specification
- For applications with high output drive and light bus loading
- Non-inverting
- 3-state output sink capability  $I_{OL}$  = 64 mA and source  $I_{OH}$  = 15 mA
- Inputs and outputs on separate sides simplifies board layout
- Combined functions reduce part count and enhance system performance
- Industrial temperature range available (–40 °C to +85 °C)

## 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
N74F656AD	0 °C to 70 °C	SO24	plastic small outline package; 24 leads; body width 7.5 mm	SOT137-1
I74F656AD	–40 °C to +85 °C			

4. Functional diagram



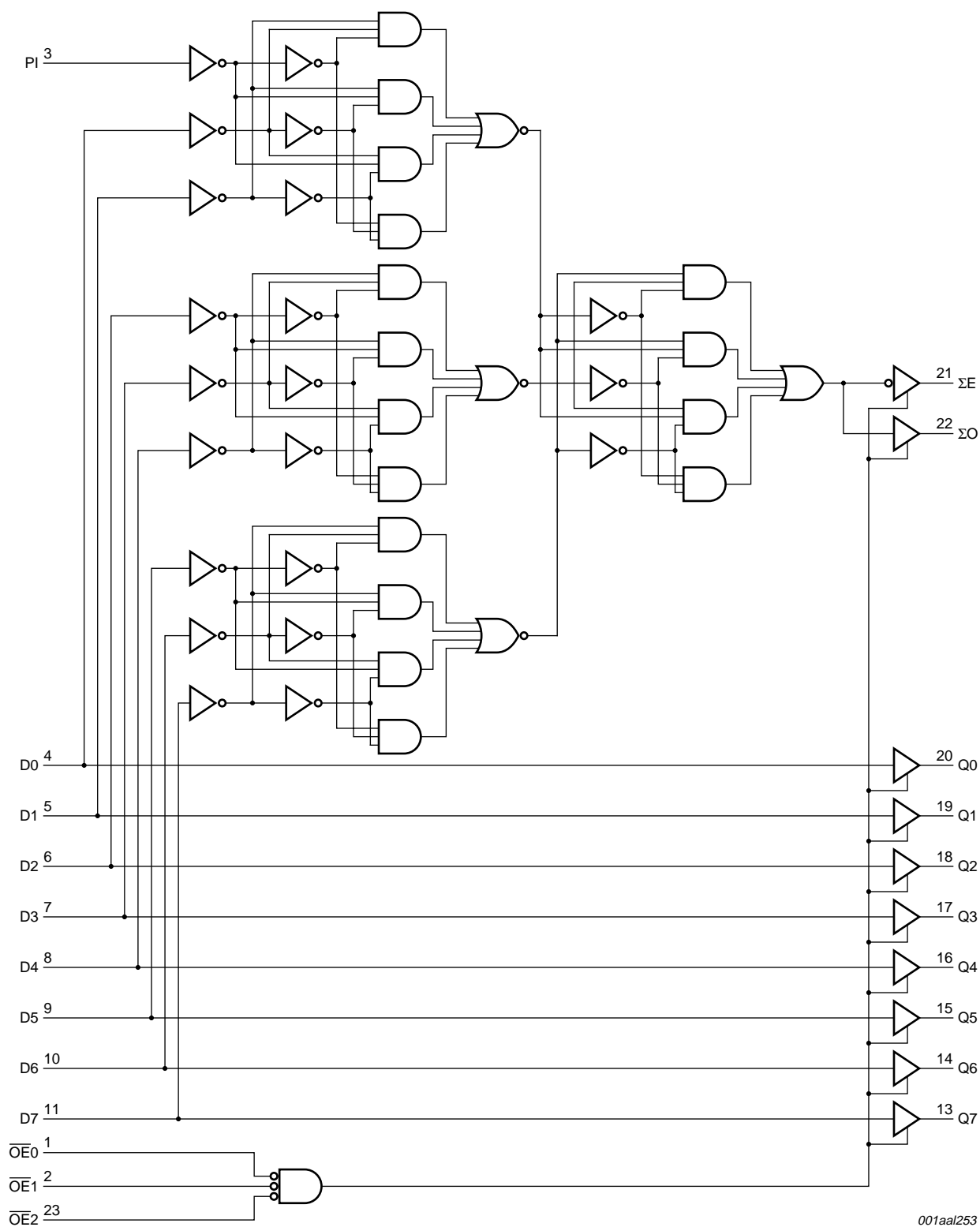
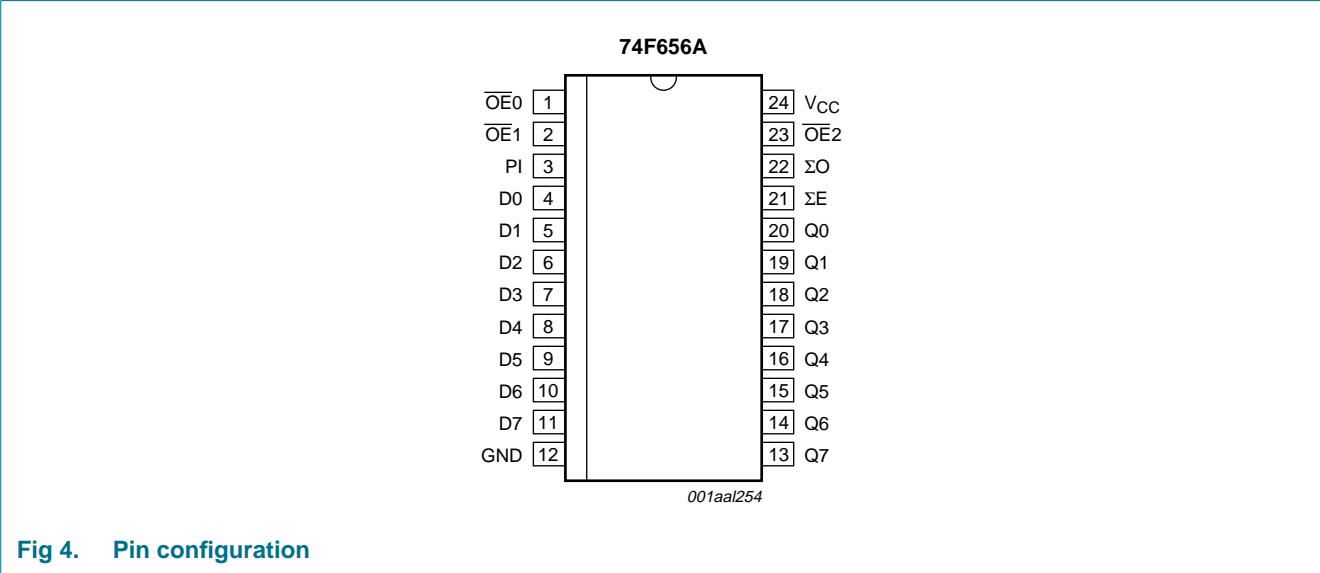


Fig 3. Logic diagram

5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description	Unit load HIGH/LOW	Load value <sup>[1]</sup> HIGH/LOW
OE0	1	output enable input (active LOW)	1.0/0.033	20 μA/20 μA
OE1	2	output enable input (active LOW)	1.0/0.033	20 μA/20 μA
PI	3	parity input	1.0/0.033	20 μA/20 μA
D0 to D7	4, 5, 6, 7, 8, 9, 10, 11	data input	2.0/0.066	40 μA/40 μA
GND	12	ground (0 V)		
Q0 to Q7	20, 19, 18, 17, 16, 15, 14, 13	data output	750/106.7	15 mA/64 mA
ΣE	21	even parity output	750/106.7	15 mA/64 mA
ΣO	22	odd parity output	750/106.7	15 mA/64 mA
OE2	23	output enable input (active LOW)	1.0/0.033	20 μA/20 μA
VCC	24	supply voltage		

[1] One FAST Unit Load (UL) is defined as 20 μA in HIGH state, 0.6 μA in LOW state.

## 6. Functional description

### 6.1 Function table

Table 3. Function selection<sup>[1]</sup>

Input				Output	Status
OE0	OE1	OE2	Dn	Qn	
L	L	L	L	L	transparent
L	L	L	H	H	
H	X	X	X	Z	disabled
X	H	X	X	Z	
X	X	H	X	Z	

[1] H = HIGH voltage level;  
 L = LOW voltage level;  
 X = don't care;  
 Z = high-impedance OFF-state.

Table 4. Function parity outputs<sup>[1]</sup>

Inputs	State	Parity output	
		$\Sigma E$	$\Sigma O$
Even number of inputs (0, 2, 4, 6, 8)	H	H	L
Odd number of inputs (1, 3, 5, 7, 9)	H	L	H
Any OE <sub>n</sub>	H	Z	Z

[1] H = HIGH voltage level;  
 L = LOW voltage level;  
 Z = high-impedance OFF-state.

## 7. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7.0	V
$V_I$	input voltage		[1] -0.5	+7.0	V
$V_O$	output voltage	output in HIGH-state	[1] -0.5	$V_{CC}$	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-30	+5	mA
$I_O$	output current	output in LOW-state	-	128	mA
$T_{amb}$	ambient temperature	in free-air	[2]		
		commercial	0	70	°C
		industrial	-40	+85	°C
$T_{stg}$	storage temperature		-65	+150	°C

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

## 8. Recommended operating conditions

**Table 6. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		4.5	5.0	5.5	V
$V_{IH}$	HIGH-level input voltage		2.0	-	-	V
$V_{IL}$	LOW-level input voltage		-	-	0.8	V
$I_{IK}$	input clamping current		-	-	-18	mA
$I_{OH}$	HIGH-level output current		-15	-	-	mA
$I_{OL}$	LOW-level output current		-	-	64	mA

## 9. Static characteristics

**Table 7. Static characteristics**

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$V_{IK}$	input clamping voltage	$V_{CC} = 4.5$ V; $I_{IK} = -18$ mA	-1.2	-0.73	-	-1.2	-	V
$V_{OH}$	HIGH-level output voltage	$V_{CC} = 4.5$ V; $V_{IL} = 0.8$ V; $V_{IH} = 2.0$ V						
		$I_{OH} = -3$ mA						
		$V_{CC} = \pm 10$ %	-	-	-	2.4	-	V
		$V_{CC} = \pm 5$ %	-	3.3	-	2.7	-	V
		$I_{OH} = -15$ mA						
		$V_{CC} = \pm 10$ %	-	-	-	2.0	-	V

Table 7. Static characteristics ...continued

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
V <sub>OL</sub>	LOW-level output voltage	V <sub>CC</sub> = 4.5 V; V <sub>IL</sub> = 0.8 V; V <sub>IH</sub> = 2.0 V						
		I <sub>OL</sub> = 64 mA						
		V <sub>CC</sub> = ±10 %	-	-	-	-	0.55	V
		V <sub>CC</sub> = ±5 %	-	0.42	-	-	0.55	V
I <sub>I</sub>	input leakage current	V <sub>CC</sub> = 0 V; V <sub>I</sub> = 7.0 V	-	-	-	-	100	µA
I <sub>IH</sub>	HIGH-level input current	V <sub>CC</sub> = 5.5 V; V <sub>I</sub> = 2.7 V; commercial						
		pin Dn	-	-	-	-	40	µA
		pin PI, $\overline{\text{OEn}}$	-	-	-	-	20	µA
		V <sub>CC</sub> = 5.5 V; V <sub>I</sub> = 2.7 V; industrial						
		pin Dn	-	-	-	-	80	µA
		pin PI, $\overline{\text{OEn}}$	-	-	-	-	40	µA
I <sub>IL</sub>	LOW-level input current	V <sub>CC</sub> = 5.5 V; V <sub>I</sub> = 0.5 V						
		pin Dn	-	-	-	-	–40	µA
		pin PI, $\overline{\text{OEn}}$	-	-	-	-	–20	µA
I <sub>OZ</sub>	OFF-state output current	V <sub>CC</sub> = 5.5 V						
		V <sub>O</sub> = 2.7 V	-	-	-	-	50	µA
		V <sub>O</sub> = 0.5 V	-	-	-	-	–50	µA
I <sub>O</sub>	output current	V <sub>CC</sub> = 5.5 V <sup>[2]</sup>	-	-	-	–100	–225	mA
I <sub>CC</sub>	supply current	V <sub>CC</sub> = 5.5 V; V <sub>I</sub> = GND or V <sub>CC</sub>						
		outputs HIGH-state	-	50	-	-	80	mA
		outputs LOW-state	-	78	-	-	110	mA
		outputs OFF-state	-	83	-	-	90	mA

[1] All typical values are measured at V<sub>CC</sub> = 5 V.

[2] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

## 10. Dynamic characteristics

Table 8. Dynamic characteristics

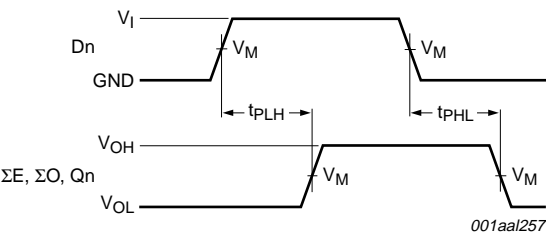
GND = 0 V; for test circuit, see [Figure 7](#).

Symbol	Parameter	Conditions	25 °C; V <sub>CC</sub> = 5.0 V			0 °C to 70 °C; V <sub>CC</sub> = 5.0 V ± 0.5 V		–40 °C to +85 °C; V <sub>CC</sub> = 5.0 V ± 0.5 V		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t <sub>PLH</sub>	LOW to HIGH propagation delay	Dn to Qn; see <a href="#">Figure 5</a>	2.0	4.0	6.5	2.0	7.0	2.0	8.0	ns
		Dn to ΣE, ΣO; see <a href="#">Figure 5</a>	5.5	10.0	13.0	5.5	14.0	4.5	16.5	ns
t <sub>PHL</sub>	HIGH to LOW propagation delay	Dn to Qn; see <a href="#">Figure 5</a>	2.5	5.5	7.0	2.5	7.5	2.5	9.0	ns
		Dn to ΣE, ΣO; see <a href="#">Figure 5</a>	5.5	11.0	14.5	5.5	16.5	5.5	18.0	ns
t <sub>PZH</sub>	OFF-state to HIGH propagation delay	$\overline{\text{OEn}}$ to Qn; see <a href="#">Figure 6</a>	3.5	7.0	10.5	3.5	11.5	3.0	13.0	ns

**Table 8. Dynamic characteristics ...continued**  
*GND = 0 V; for test circuit, see Figure 7.*

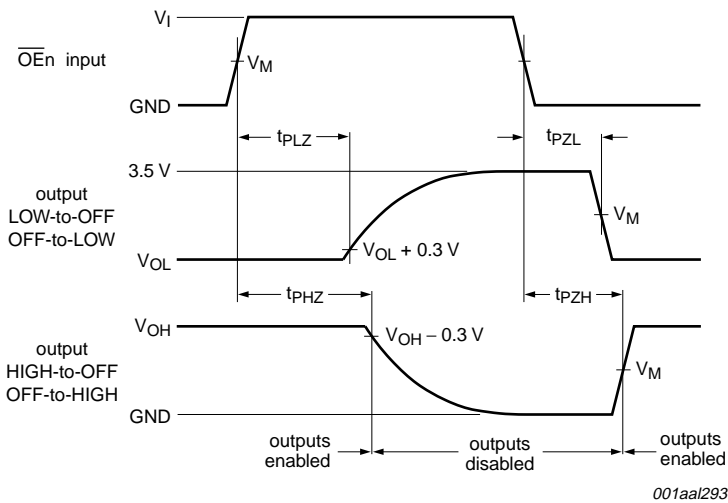
Symbol	Parameter	Conditions	25 °C; V <sub>CC</sub> = 5.0 V			0 °C to 70 °C; V <sub>CC</sub> = 5.0 V ± 0.5 V		–40 °C to +85 °C; V <sub>CC</sub> = 5.0 V ± 0.5 V		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t <sub>PZL</sub>	OFF-state to LOW propagation delay	$\overline{\text{OEn}}$ to Qn; see Figure 6	4.0	8.0	11.0	4.5	12.0	4.0	13.5	ns
t <sub>PHZ</sub>	HIGH to OFF-state propagation delay	$\overline{\text{OEn}}$ to Qn; see Figure 6	1.5	4.5	8.0	1.5	9.0	1.5	10.0	ns
t <sub>PLZ</sub>	LOW to OFF-state propagation delay	$\overline{\text{OEn}}$ to Qn; see Figure 6	2.0	5.0	8.0	2.0	9.0	1.5	10.0	ns

## 11. Waveforms



$V_M = 1.5\text{ V}$

**Fig 5. Propagation delay input Dn to output Qn, ΣE, ΣO**



$V_M = 1.5\text{ V}$

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 6. 3-state output enable and disable times**



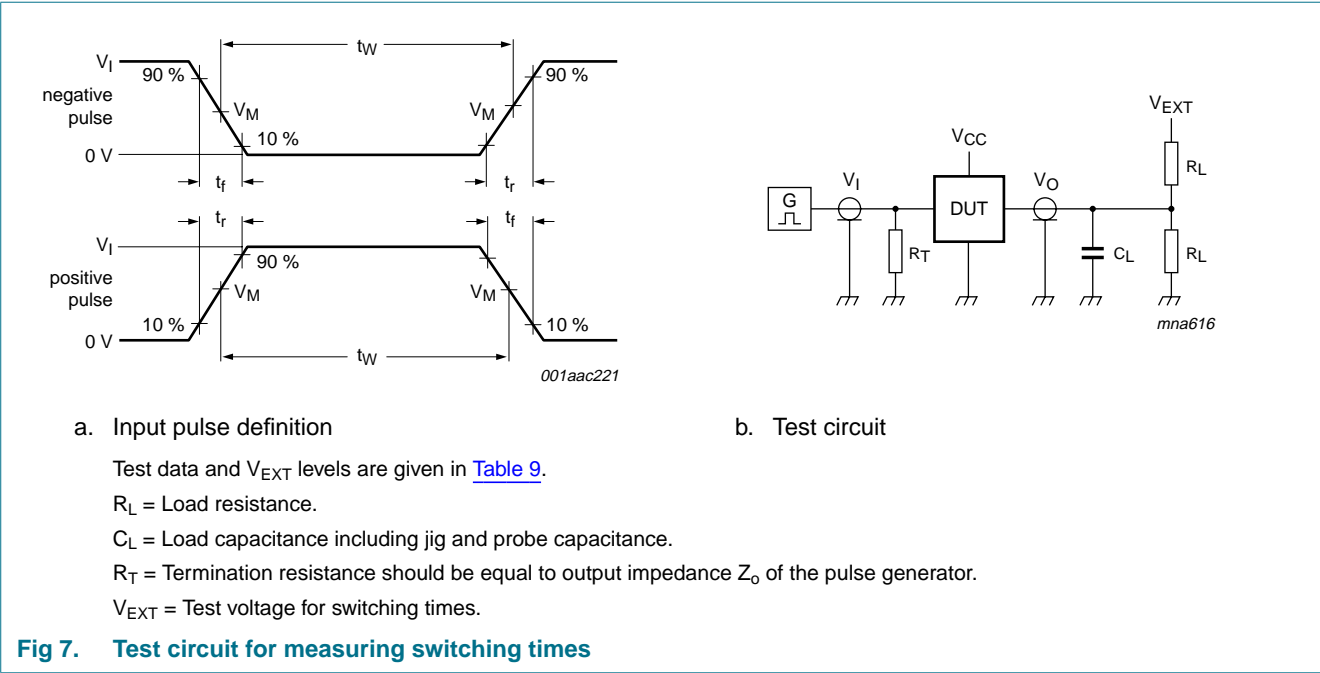


Fig 7. Test circuit for measuring switching times

Table 9. Test data

Input				Load		$V_{EXT}$		
$V_I$	$f_I$	$t_W$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
3.0 V	1 MHz	500 ns	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	open	7.0 V

12. Package outline

SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1

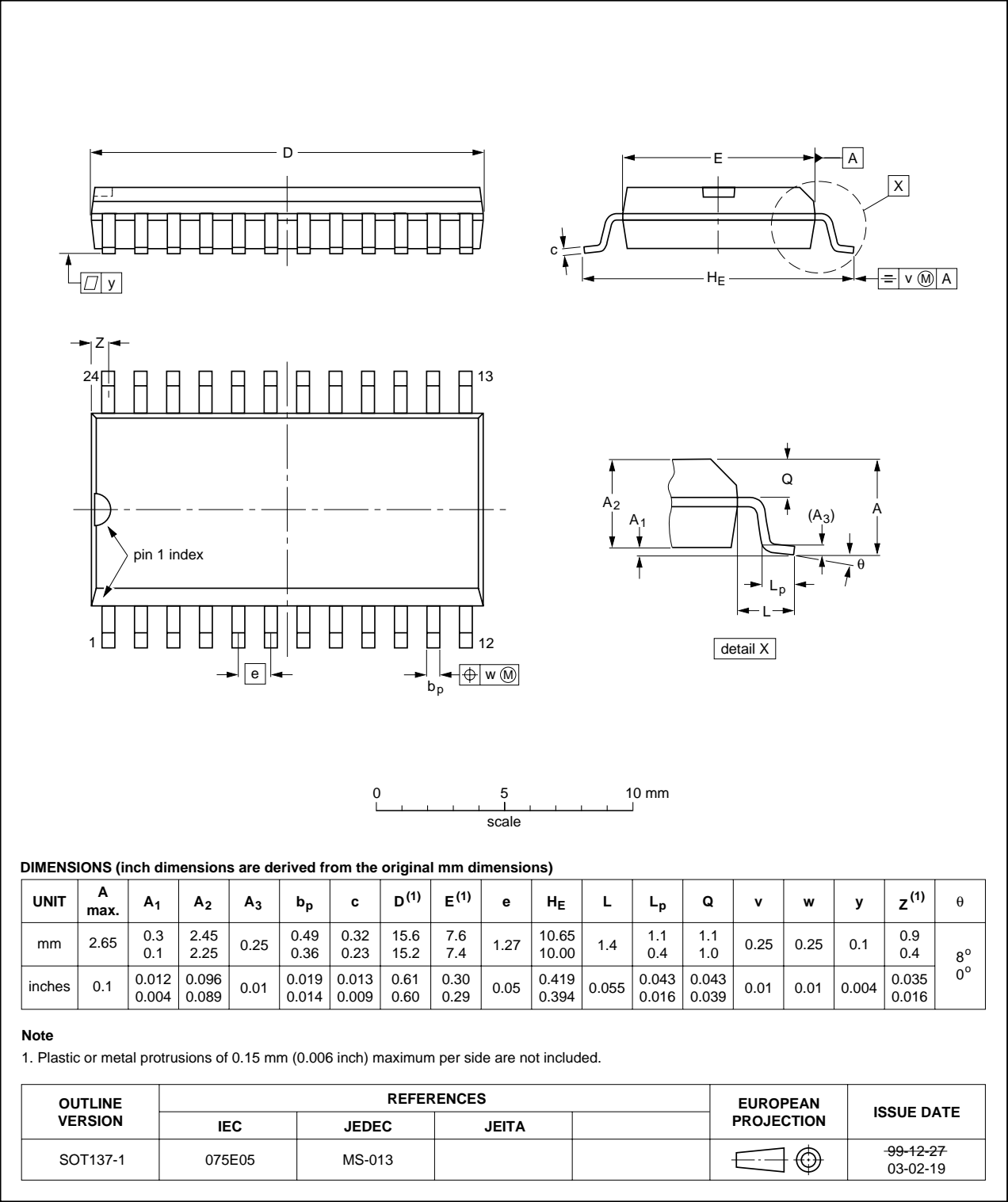


Fig 8. Package outline SOT137-1 (SO24)

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
PCB	Printed-Circuit Board

## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74F656A_4	20100205	Product data sheet	-	74F656A_3
Modifications:	<ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li><li>• DIP 24 (SOT222-1) package removed from <a href="#">Section 3 “Ordering information”</a> and <a href="#">Section 12 “Package outline”</a></li></ul>			
74F656A_3	20000630	Product specification	-	74F656A_2
74F656A_2	19910717	Product specification	-	-

## 15. Legal information

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

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